

## **Advance Product Change Notification**

202108026A : Qualification of Substrate Supplier Daeduck (DDE) for

i.MX 6Dual/6Quad, i.MX 6DualPlus/6QuadPlus, i.MX 8QuadMax, i.MX

8QuadPlus	, i.MX	8DualXPlus,	i.MX	8QuadXPlus
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<b>Note:</b> This Proprietary	notice is NXI			
Issue Date: Change Ca	: Sep 03, 202 <b>tegory</b>	1		
☐ Wafer Fab Process	Assembly Process	Product Marking	Test Process	Design
<ul><li>Wafer</li><li>Fab</li><li>Materials</li></ul>	<ul><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li><li>✓</li>&lt;</ul>	Mechanical Specification	Test Equipment	🗆 Errata
<ul><li>Wafer</li><li>Fab</li><li>Location</li><li>Firmware</li></ul>	<ul><li>Assembly</li><li>Location</li><li>Other</li></ul>	Packing/Shipping/Labeling	Test Location	Electrical spec./Test coverage

# **PCN Overview**

## Description

This Advanced Product Change Notification is to announce the planned qualification of Daeduck (DDE) substrate supplier for the devices listed in this notification.

Planned dates for Final PCN issuance for each product family are included in attached files, based on qualification timing. To limit supply interruptions, the final PCN notifications for select product families will include compressed implementation schedules. Please contact your NXP sales and marketing representatives for specific details.

DDE substrate material is equivalent to existing substrate suppliers with no change to the substrate design.

Please refer to the attachments for change details and qualification plans that will be included in the final PCN's.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-09, SEM-PA-16 **Reason** DDE substrate supplier to be qualified as assurance of supply. **Identification of Affected Products** Product identification does not change

#### **Product Availability**

#### Sample Information

Samples availability differs by product-see attached sample plan Please see attached "Details of Change" file for prototype sample part number availability and timing. **Production** 

Shipment dates are product specific, see attached plan

### Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on fit or function, reliability or quality. Form changes due to a difference in color for the DDE substrate.

**Disposition of Old Products** Existing inventory will be shipped until depleted

### Additional information

Self qualification: <u>view online</u> Additional documents: <u>view online</u>

### **Timing and Logistics**

The Self Qualification Report will be ready on Jan 07, 2022.

The Final PCN is planned to be issued on: Jan 07, 2022.

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Oct 03, 2021.

Please see attached "Details of Change" file for SQR Planned Date and Planned date for final PCN

### **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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NXP Semiconductors

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